

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1. (currently amended) A method for detecting electrical defects on test structures of a semiconductor die, the test structures including a plurality of electrically-isolated test structures and a plurality of non-electrically-isolated test structures, the test structures each having a portion located partially within a scan area, the method comprising:
  - a. scanning the portion of the test structures located within the scan area to obtain voltage contrast images of the test structures' portions; and
  - b. ~~in a multi pixel processor~~, analyzing the obtained voltage contrast images to determine whether there are defects present within the test structures, wherein the obtained voltage contrast images have a pixel resolution size which is greater than a dimension of the test structures.
2. (currently amended) A method as recited in claim 1 wherein the ~~multi pixel processor operates with obtained voltage contrast images have pixel resolution sizes in a range of about 25nm to 2000nm~~
3. (currently amended) A method as recited in claim 1, wherein the ~~multi pixel processor operates with obtained voltage contrast images have~~ a pixel size nominally equivalent to two times a width of the test structure's line width to maximize throughput at optimal signal to noise sensitivity.
4. (original) A method as recited in claim 1 wherein the scanned portions of the electrically isolated test structures are expected to have substantially a same first brightness level, and the scanned portions of the non-electrically isolated test structures are expected to have substantially a same second brightness level that differs from the first brightness level.
5. (original) A method as recited in claim 1 wherein the obtained voltage contrast images are analyzed by comparing them to a plurality of reference images.

6. (original) A method as recited in claim 3 wherein the reference images are generated from a database.

7. (original) A method as recited in claim 6 wherein the database comprises expected voltage contrast images.

8. (original) A method as recited in claim 6 wherein the database is a design database utilized to fabricate the semiconductor die.

9. (original) A method as recited in claim 1 wherein the obtained voltage contrast images are analyzed by comparing them to a truth table.

10. (original) A method as recited in claim 9 wherein the truth table includes expected brightness levels for the scanned portions of the test structures.

11. (original) A method as recited in claim 1 wherein the obtained voltage contrast images are analyzed by comparing them to a plurality of images from an adjacent semiconductor die.

12. (original) A method as recited in claim 1 wherein the obtained voltage contrast images are analyzed by comparing them to a plurality of images from an adjacent other plurality of test structures on the semiconductor die.

13. (original) A method as recited in claim 10 wherein the comparison is accomplished in an array mode.

14. (original) A method as recited in claim 1 wherein the scanning is accomplished with an electron beam.

15. (currently amended) A computer-readable medium comprising computer code for detecting electrical defects on test structures of a semiconductor die, the test structures including a plurality of electrically-isolated test structures and a plurality of non-electrically-isolated test structures, the test structures each having a portion located partially within a scan area, the computer-readable medium comprising:

computer code for obtaining voltage contrast images of the portions of the test structures located within the scan area; and

computer code for analyzing the obtained voltage contrast images to determine whether there are defects present within the test structures, the images being analyzed in a multi-pixel fashion wherein the obtained voltage contrast images have a pixel resolution size which is greater than a dimension of the test structures.

16. (original) A computer-readable medium as recited in claim 15 wherein the images of the portions of the electrically isolated test structures are expected to have substantially a same first brightness level, and the image of the portions of the non-electrically isolated test structures are expected to have substantially a same second brightness level that differs from the first brightness level.

17. (original) A computer-readable medium as recited in claim 15 wherein the obtained voltage contrast images are analyzed by comparing them to a plurality of reference images.

18. (original) A computer-readable medium as recited in claim 17 wherein the reference images are generated from a database.

19. (original) A computer-readable medium as recited in claim 18 wherein the database comprises expected voltage contrast images.

20. (original) A computer-readable medium as recited in claim 18 wherein the database is a design database utilized to fabricate the semiconductor die.

21. (original) A computer-readable medium as recited in claim 15 wherein the obtained voltage contrast images are analyzed by comparing them to a truth table.

22. (original) A computer-readable medium as recited in claim 21 wherein the truth table includes expected brightness levels for the scanned portions of the test structures.

23. (original) A computer-readable medium as recited in claim 15 wherein the obtained voltage contrast images are analyzed by comparing them to a plurality of images from an adjacent semiconductor die.

24. (original) A computer-readable medium as recited in claim 15 wherein the obtained voltage contrast images are analyzed by comparing them to a plurality of images from an adjacent other plurality of test structures on the semiconductor die.

25. (original) A computer-readable medium as recited in claim 24 wherein the comparison is accomplished in an array mode.

26. (new) A computer-readable medium as recited in claim 15, wherein the obtained voltage contrast images have pixel resolution sizes in a range of about 25nm to 2000nm

27. (new) A computer-readable medium as recited in claim 15, wherein the obtained voltage contrast images have a pixel size nominally equivalent to two times a width of the test structure's line width to maximize throughput at optimal signal to noise sensitivity.